

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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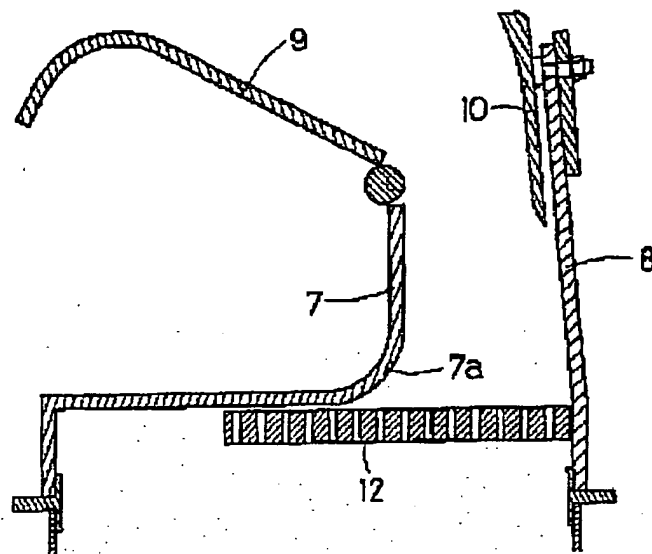
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APPLICANT : MASUTETSUKU:KK;

INVENTOR : NISHIMURA TETSUO;

INT.CL. : H05K 3/34 B23K 1/08

TITLE : JET SOLDERING DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a jet soldering device which does not require double operation and enables highly reliable batch soldering of a large amount of solder while preventing bridge defects.

SOLUTION: This device has a nozzle device which is enclosed with a front vertical part 7, a rear vertical part 8 and a side plate, and a rear current plate 10 is extended to an upper end of the rear vertical part 8 to enable the height to be adjusted. An L-shaped front current plate 9 of a large curvature is connected to an upper end of the front rise 7 to oscillate freely and a top panel rear part of the rear current plate 10 is cut off. A bypass wherein a small amount of solder can pass through is formed between it and the rear rise 8. A part of a wave of molten solder formed along the rear current plate 10 is made to join molten solder passing through a bypass via an upper surface of the rear current plate 10 and to overflow to a rear.

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